RD50 Collaboration board meeting

CERN, 14.11.2012

Agenda

- Report of the spokespersons (G. Casse, M. Moll)
- Approval of the minutes of the CB meeting
- Definition of observer status
- Application for membership
 - □ University of Seville (Francisco Rogelio) observer
 - □ LPNHE Paris (Giovanni Calderini) membership
 - □ DESY (Doris Eckstein) membership
- ☐ Financial report (M. Glaser, M. Moll)
 - Budget status
 - Financial status of RD50 projects
 - □ Plans for funding new projects in 2013
- Status review of the RD50 projects
- Preparation of status report for 2011/2012
- Issues regarding next RD50 meetings
- Conferences with RD50 participation
- AOB



Proposal of observer status definition

Definition:

RD50 observers are institutions that are invited to participate in RD50 Workshops and share their research results with RD50 collaboration members. The name of the institute together with a contact person will be listed on the RD50 website indicating the observer status of the institute. Members of the institute will be placed on the RD50 observers mailing list upon request.

Observers do not participate in the RD50 Collaboration Board, they do not have the right to vote on any RD50 decision, they do not pay the collaboration fee and they are not listed as co-authors on common RD50 publications. They might participate in RD50 common projects, but they will not be taken into account for the calculation of the RD50 financial support to the project (which depends on the number of the participating RD50 institutes).

Appointment of observers:

Any member of the CB has the right to propose an institution for the observer status, which then has to be approved by a vote in the CB.

RD50 projects in 2012

- PROPOSED: Fabrication of new p-type pixel detectors with enhanced multiplication effect in the n-type electrodes (G. Pellegrini):
- APPROVED: Production at CiS of planar pixel sensors and diodes with n-in-p technology and characterization of main radiation-induced defects (M. Bruzzi).

Review of the RD50 projects

Project	Coordinator
(1) 2011-01 Silicon Wafers at TOPSIL	Michael Moll
(2) 2011-02 Bump bonding of ATLAS Pixel Sensors	Daniel Muenstermann, Dortmund
(3) 2011-03 Slim Edges	Hartmut Sadrozinski
(4) 2011-04 Thin p-type pixel from CIS	Anna Macchiolo
(5) 2011-05 Low resistance strip sensors	CNM

Project	Coordinator
(1) 2010-01 4 inch wafers with Micron for ministrip sensors	Gianluigi Casse, Liverpool
(2) 2010-02 n-in-n pixel sensors with CIS	Daniel Muenstermann, Dortmund
(3) 2010-3 CNM- P-type sensors with trench	Pelegrini

Project	Coordinator
(1) Project on CIS Sensors	A.Macchiolo (MPI Munich)
(3) Silicon sensor production with Micron	Gianluigi Casse
(4) MCZ silicon wafers	Michael Moll